

	Subclass	ISSUE CLASSIFICATION

PATENT NUMBER

U.S. UTILITY Patent Application

O.I.P.E.	PATENT DATE
SCANNED <u>TR3</u> O.A. Am	

APPLICATION NO. 09/964709	CONT/PRIOR	CLASS 257	SUBCLASS 706	ART UNIT 281 3834	EXAMINER <i>CHAMBLISS</i> <i>Chambliss</i>
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APPENDIX

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THE

Method of improving thermal performance in flip-chip/integral heat spreader packages using low modulus thermal interface material

PTO-2040
1388

ISSUING CLASSIFICATION

TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	(Assistant Examiner) _____ (Date) _____			NOTICE OF ALLOWANCE MAILED	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent No. _____				ISSUE FEE	
<input type="checkbox"/> The terminal _____ months of _____ (Primary Examiner) _____ (Date) _____	Amount Due	Date Paid			
			ISSUE BATCH NUMBER		

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